

Parker Chomerics CHO-BOND SV712 Conductive Epoxy

Category : Polymer , Adhesive , Thermoset , Epoxy , Epoxy, Electrically Conductive

Material Notes:

CHO-BOND® 700 Series Adhesives for Microelectronics Packaging; these pure silver-filled epoxy pastes are designed to meet the demanding requirements of semiconductor and microelectronic packaging. They are one-component systems with a unique combination of excellent die shear strength, low coefficients of thermal expansion, ionic purity, and high thermal and electrical conductivities. Each offers and extended working life with viscosity and thixotropy suitable for both time/pressure and positive displacement dispensing methods. CHO-BOND® SV712 die attach adhesive has been optimized for high-speed, automated dispensing. It exhibits no resin bleed out on a variety of substrates and metallizations. Information provided by Chomerics

Order this product through the following link:

http://www.lookpolymers.com/polymer_Parker-Chomerics-CHO-BOND-SV712-Conductive-Epoxy.php

Physical Properties	Metric	English	Comments
Specific Gravity	3.00 - 3.60 g/cc	3.00 - 3.60 g/cc	
Volatile Organic Compounds (VOC) Content	0.00 g/l	0.00 g/l	
Solubility in Water	0.00 %	0.00 %	Insoluble
Thickness	25.4 microns	1.00 mil	Recommended

Mechanical Properties	Metric	English	Comments
Shear Strength	>= 7.58 MPa	>= 1100 psi	Lap
	>= 33.1 MPa	>= 4800 psi	Die

Thermal Properties	Metric	English	Comments
Maximum Service Temperature, Air	150 °C	302 °F	
Minimum Service Temperature, Air	-45.0 °C	-49.0 °F	
Flash Point	>= 93.3 °C	>= 200 °F	

Component Elements Properties	Metric	English	Comments
Silver, Ag	60 - 85 %	60 - 85 %	

Electrical Properties	Metric	English	Comments
Volume Resistivity	<= 0.00040 ohm-cm	<= 0.00040 ohm-cm	DC

Processing Properties	Metric	English	Comments
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Processing Properties	^{70.0 min} Metric	^{0.500 hour} English	Comments
	@Temperature 150 °C	@Temperature 302 °F	
	60.0 min	1.00 hour	
	@Temperature 125 °C	@Temperature 257 °F	
Shelf Life	12.0 Month	12.0 Month	
	@Temperature -40.0 °C	@Temperature -40.0 °F	

Descriptive Properties	Value	Comments
Amine Compound Proprietary wt. % Max	5	
Binder	Epoxy	
Consistency	Thixotropic Paste	
Epoxy Resin, wt %	15 - 25	
Filler	Ag	
Mix Ratio	1-part	
o-Cresyl glycidyle ether wt. % Max	10	
Work Life	4 weeks	

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com

Email : sales@lookpolymers.com

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215,Fengxian District, Shanghai City,China